HOCH Systemy Kominowe Sp. z o.o. Sp. k.
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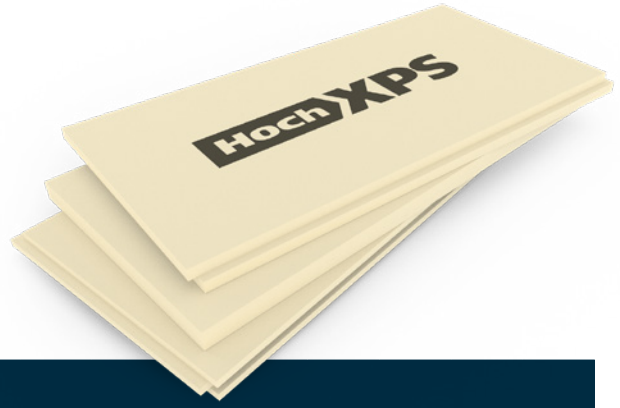
HOCH XPS TECHNICAL SHEET



Technical parameters	Symbol / Unit	THICKNESS																			
		XPS200		XPS300											XPS500				XPS700		
		20	30	40	50	60	80	100	120	140	150	160	180	200	50	80	100	120	50	80	100
Thermal conductivity coefficient	λ_D [W/mK]	≤ 0.034	≤ 0.032	≤ 0.032	≤ 0.032	≤ 0.032	≤ 0.034	≤ 0.034	≤ 0.036	≤ 0.036	≤ 0.036	≤ 0.036	≤ 0.036	≤ 0.036	≤ 0.034	≤ 0.034	≤ 0.036	≤ 0.036	≤ 0.034	≤ 0.034	≤ 0.036
Thermal resistance	R_D [m²K/W]	0.55	0.90	1.25	1.55	1.85	2.35	2.90	3.30	3.85	4.15	4.40	5.00	5.50	1.45	2.35	2.75	3.30	1.45	2.35	2.75
Thickness	d_N [mm]	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1	T1
Fire reaction class	Euroclass	F	F	F	F	F	F	F	F	F	F	F	F	F	F	F	F	F	F	F	F
Dimensional stability	DS(TH) [%]	≤ 5	≤ 5	≤ 5	≤ 5	≤ 5	≤ 5	≤ 5	≤ 5	-	≤ 5	-	-	-	-	-	-	-	-	-	-
Freeze resistance — defrosting after water absorbability test with long lasting diffusion	FTCD [%]	-	-	-	1	1	1	1	1	-	1	-	-	-	-	-	-	-	-	-	-
Resistance to freezing — defrosting after testing long lasting water absorption by immersion	FTCI [%]	-	-	-	1	1	1	1	1	-	1	-	-	-	-	-	-	-	-	-	-
Compressive strength at 10% strain	CS (10/Y) [kPa]	≥ 200	≥ 200	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 300	≥ 500	≥ 500	≥ 500	≥ 500	≥ 700	≥ 700	≥ 700
Water absorbability when submerged for a long time	WL(T) [%]	≤ 3.0	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7	≤ 0.7
Water absorbability at long-term diffusion	WD(V) [%]	-	-	-	≤ 2	≤ 2	≤ 1	≤ 1	≤ 1	-	≤ 1	-	-	-	-	-	-	-	-	-	-
Diffusion resistance factor	MU	150	150	-	150	150	150	150	150		150	-	-	-	-	-	-	-	-	-	-

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PACKAGING

HOCH XPS boards are packed in a package wrapped in plastic and then stored on a pallet.

XPS board thickness [mm]	PACKAGE				PALETTE				
	Number of boards per package [pcs]	Area of boards per package [m^2]	Volume of boards in a package [m^3]	Package height [m]	Number of packages per pallet [pcs]	Number of boards per pallet [pcs]	Surface of boards on a pallet [m^2]	Volume of boards per pallet [m^3]	Height with sleepers [m]
20	20	15	0.3	0.4	12	240	180	3.6	2.48
30	14	10.5	0.315	0.42	12	168	126	3.78	2.60
40	10	7.5	0.3	0.4	12	120	90	3.6	2.48
50	8	6	0.3	0.4	12	96	72	3.6	2.48
60	7	5.25	0.315	0.42	12	84	63	3.78	2.60
80	5	3.75	0.3	0.4	12	60	45	3.6	2.48
100	4	3	0.3	0.4	12	48	36	3.6	2.48
120	4	3	0.36	0.48	10	40	30	3.6	2.48
140	3	2.25	0.315	0.42	12	36	27	3.78	2.6
150	3	2.25	0.3375	0.45	10	30	22.5	3.375	2.33
160	3	2.25	0.36	0.48	10	30	22.5	3.6	2.48
180	2	1.5	0.27	0.36	14	28	21	3.78	2.6
200	2	1.5	0.3	0.40	12	24	18	3.6	2.48

OVERALL DIMENSIONS OF THE BOARDS		
Edge finishing	Length [mm]	Width [mm]
I	1,250	600
L	1,265	615
PW	1,265	615

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PRODUCT APPLICATION:

Thermal insulation in construction:

- thermal insulation of foundations and basement walls,
- thermal insulation of floors and floorings,
- thermal insulation of building façades,
- thermal insulation of interior walls,
- thermal insulation of pitched roofs and inverted roofs (flat roofs),
- thermal insulation of terraces and balconies.

PRODUCT ADVANTAGES

The main advantages of XPS boards are:

- very low thermal conductivity coefficient,
- closed-cell structure, resulting in a very low absorbability,
- high compressive strength,
- ease of board installation,
- full recycling (no waste),
- cellular structure, filled with air, maintains thermal insulation performance stable over time,
- Polish product.

TRANSPORT AND STORAGE

It is not permitted to transport XPS boards with other materials that may adversely affect mechanical or physico-chemical properties, such as solvents, paints, fuels or other hazardous materials that may move around in the load compartment. It is mandatory to prohibit smoking and usage of open fire in the load compartment where the XPS boards are located.

Extruded polystyrene boards are recommended to be stored in ventilated areas. Do not store XPS boards in one room with flammable or volatile products. This product is degraded under the influence of UV radiation. Contact with open fire must be absolutely avoided.

INSTALLATION

Solvent adhesives in contact with XPS HOCH boards cause undesirable effects; destruction of XPS boards occurs. Before installation, check whether the adhesive can be used for polystyrene foam. Boards exposed to UV radiation may degrade; it is imperative to cover them with bright UV-impermeable material. If you glue the boards, the surface should be rough in order to improve the board–glue bonding. Application of the product at low temperatures requires a sufficiently large space between boards to maintain proper expansion.

RESPONSIBILITY

The information contained in this document is for informational purposes only, therefore the Manufacturer is not responsible for its content. The Manufacturer recommends that transport and storage be carried out in accordance with this document, but the use and application of these products are not controlled by the Manufacturer. The customer is responsible for waste management in accordance with applicable law.

MANUFACTURER

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